

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Application of:
Cheung, et al.

Serial No.: 09/609,347

Confirmation No.: 5540

Filed: July 5, 2000

For: Apparatus for Electro-
Chemical Deposition of
Copper Metalization With
Thermal Annealing

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Group Art Unit: 1741

Examiner: E. Smith-Hicks

12/D
TC 1700

9/10/02
SEP 24 2002

RECEIVED

CERTIFICATE OF MAILING
37 CFR 1.8

I hereby certify that this correspondence is being deposited on
September 18, 2002 with the United States Postal Service as
First Class Mail in an envelope addressed to: Commissioner
for Patents, Washington, D.C. 20231.

September 18, 2002
Date


B. Todd Patterson

RESPONSE TO OFFICE ACTION DATED JUNE 25, 2002

In response to the Office Action dated June 25, 2002, having a shortened statutory period for response set to expire on September 25, 2002, please consider this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no fee is due in conjunction with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/3421.C1/CMP/ECP/RKK, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

IN THE CLAIMS:

Please cancel claims 12-18 without prejudice.

Please amend the following claims:

1. An electro-chemical deposition system, comprising:
a mainframe having a mainframe wafer transfer robot;
a loading station disposed in connection with the mainframe;